

Product Portfolio and Features

● Essential features contained | ○ Optional features

| Product Package & Mesh Technology | | | | |
|--------------------------------------|--------------------|---------|--------------|----------|
| | Professional Basic | eDesign | Professional | Advanced |
| True 3D Mesh | | | | |
| eDesign | ● | ● | ● | ● |
| Boundary Layer Mesh (BLM), Tetra | ● | | ● | ● |
| Solid (Hexa, Prism, Pyramid, Hybrid) | | | | ● |
| 2.5D Mesh | | | | |
| Shell | | | | ● |

● Essential features contained | ○ Optional features

| Standard Injection Molding | | | | |
|--------------------------------------|--------------------|---------|--------------|----------|
| | Professional Basic | eDesign | Professional | Advanced |
| Solver Capabilities | | | | |
| Simultaneous Filling Analysis (max.) | 1 | 1 | 1 | 3 |
| Parallel Processing (PP) | 4 | 4 | 8 | 12 |
| Thermoplastic Injection Molding | ● | ● | ● | ● |
| Reaction Injection Molding (RIM) | ● | ● | ● | ● |
| Cloud Extension | ● | ● | ● | ● |
| Simulation Capabilities | | | | |
| Filling | ● | ● | ● | ● |
| Surface Defect Prediction | ● | ● | ● | ● |
| Venting Analysis | ● | ● | ● | ● |
| Gate Location | ● | ● | ● | ● |
| Cold & Hot Runners | ● | ● | ● | ● |
| Runner Balancing | ● | ● | ● | ● |
| Packing | | ● | ● | ● |
| Cooling | | ● | ● | ● |
| Transient Mold Cooling or Heating | | ● | ● | ● |
| Conformal Cooling | | ● | ● | ● |
| 3D Coolant CFD | | ○ | ● | ● |
| Rapid Temperature Cycling | | ● | ● | ● |
| Induction Heating | | ● | ● | ● |
| Heating Elements | | ● | ● | ● |
| Warpage | | ● | ● | ● |
| Insert Molding | ● | ● | ● | ● |
| Multi-shot Sequential Molding | | ● | ● | ● |

● Essential features contained | ○ Optional features

| Solution Add-on | | | | |
|---|--------------------|---------|--------------|----------|
| | Professional Basic | eDesign | Professional | Advanced |
| CAD Interoperability | | | | |
| SYNC | ○ | ○ | ○ | ○ |
| Moldex3D CADdoctor | ○ | ○ | ○ | ○ |
| Moldex3D Cooling Channel Designer (CCD) | | ○ | ○ | ○ |
| Fiber Reinforced Plastics | | | | |
| Fiber | ○ | ○ | ○ | ○ |
| Stress | | ○ | ○ | ○ |
| FEA Interface | ○ | ○ | ○ | ○ |
| Micromechanics Interface | ○ | ○ | ○ | ○ |
| Moldex3D Digimat-RP | ○ | ○ | ○ | ○ |
| DOE | | | | |
| Expert | | ○ | ○ | ○ |
| Thermal Management | | | | |
| Advanced Hot Runner | | ○ | ○ | ○ |
| In-Mold Decoration(IMD) | | | ○ | ○ |
| Optical | | | | |
| Optics | | | | ○ |
| Viscoelasticity (VE) | | ○ | ○ | ○ |
| Special Molding Processes | | | | |
| Powder Injection Molding (PIM) | ○ | ○ | ○ | ○ |
| Foam Injection Molding | | ○ | ○ | ○ |
| Gas-Assisted Injection Molding (GAIM) | | | ○ | ○ |
| Water-Assisted Injection Molding (WAIM) | | | ○ | ○ |
| Co-Injection | | | ○ | ○ |
| Bi-Injection | | | ○ | ○ |
| PU Chemical Foaming | | | ○ | ○ |
| Compression Molding (CM) | | | | ○ |
| Injection Compression Molding (ICM) | | | | ○ |
| Resin Transfer Molding (RTM) | | | | ○ |

1. Moldex3D SYNC supports PTC® Creo®, NX, and SOLIDWORKS®.

2. Moldex3D FEA Interface supports Abaqus, ANSYS, MSC.Nastran, Nastran, NX Nastran, LS-DYNA, MSC.Marc, and Radioss.

3. Moldex3D Micromechanics Interface supports Digimat and CONVERSE.

4. Database: Thermoplastics materials, thermoset materials, molding materials, coolant materials, and mold materials.

| System Requirements | |
|---------------------|--|
| Platform | |
| Windows | Windows 10, 8, 7, Server 2012, 2008 R2, HPC Server 2008 R2 |
| Hardware | |
| Minimum | Intel® Core i7 processor, 16 GB RAM, and at least 1 TB free space |
| Recommended | Intel® Xeon® E5 processor, 32 GB RAM, and at least 2 TB free space |